TOSHIBA Field Effect Transistor Silicon N-Channel MOS Type (π -MOSIV)

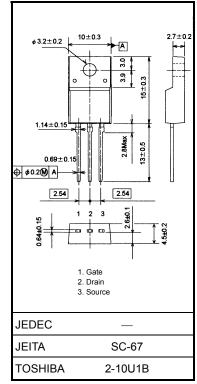
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Switching Regulator Applications

- Low drain-source ON resistance $: RDS(ON) = 1.0 \Omega(typ.)$
- High forward transfer admittance \therefore |Y_{fs}| = 6.0 S (typ.)
- Low leakage current $: I_{DSS} = 100 \,\mu A (max) (V_{DS} = 720 \,V)$
- Enhancement model $: V_{th} = 2.0 \text{ to } 4.0 \text{ V} (V_{DS} = 10 \text{ V}, \text{ ID} = 1 \text{ mA})$

Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit	
Drain-source voltage		V _{DSS}	900	V	
Drain-gate voltage (R _{GS} = 20 kΩ)		V _{DGR}	900	V	
Gate-source voltage		V _{GSS}	±30	V	
Drain current	DC (Note 1)	ID	8	А	
	Pulse (Note 1)	I _{DP}	24	A	
Drain power dissipat	ion	PD	50	W	
Single pulse avalanche energy (Note 2)		E _{AS}	1080	mJ	
Avalanche current		I _{AR}	8	А	
Repetitive avalanche energy (Note 3)		E _{AR}	5	mJ	
Channel temperature		T _{ch}	150	°C	
Storage temperature range		T _{stg}	-55~150	°C	



Weight: 1.7 g (typ.)

Thermal Characteristics

Characteristic	Symbol	Max	Unit
Thermal resistance, channel to case	R _{th (ch-c)}	2.5	°C / W
Thermal resistance, channel to ambient	R _{th (ch−a)}	62.5	°C/W

1 o

Note 1: Ensure that the channel temperature does not exceed 150°C during use of the device.

Note 2: V_DD = 90 V, T_ch = 25°C (initial), L = 30.9 mH, R_G = 25 Ω , I_{AR} = 8 A

Note 3: Repetitive rating: pulse width limited by maximum channel temperature.

This transistor is an electrostatic-sensitive device. Handle with care.



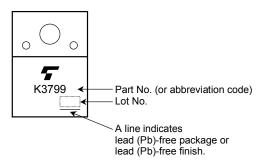
Electrical Characteristics (Ta = 25°C)

Chara	cteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	urrent	I _{GSS}	V _{GS} = ±30 V, V _{DS} = 0 V		—	±10	μA
Drain-source bre	eakdown voltage	V (BR) GSS	$I_{G} = \pm 10 \ \mu A, V_{GS} = 0 \ V$	±30	_	_	V
Drain cut-off cur	rent	I _{DSS}	V _{DS} = 720 V, V _{GS} = 0 V		_	100	μA
Drain-source bre	eakdown voltage	V (BR) DSS	I _D = 10 mA, V _{GS} = 0 V	450	—	_	V
Gate threshold v	voltage	V _{th}	V _{DS} = 10 V, I _D = 1 mA	2.0	_	4.0	V
Drain-source Of	V resistance	R _{DS (ON)}	V _{GS} = 10 V, I _D = 4 A		1.0	1.3	Ω
Forward transfe	r admittance	Y _{fs}	V _{DS} = 15 V, I _D = 4 A	3.5	6.0	_	S
Input capacitance	nput capacitance C _{iss}				2200	_	pF
Reverse transfer capacitance		C _{rss}	V _{DS} = 25 V, V _{GS} = 0 V, f = 1 MHz		45	_	
Output capacitance		C _{oss}			190	—	
Switching time	Rise time	tr	$V_{GS} = 4 A$ $V_{GS} = 4 A$ $V_{GS} = 4 A$ $U_{D} = 4 A$ U	_	25	_	
	Turn-on time	t _{on}		_	65	_	ns
	Fall time	t _f		_	20	_	. 115
	Turn-off time	t _{off}	Duty ≤ 1%, t _w = 10 µs	_	120	_	
Total gate charge (Gate-source plus gate-drain)		Qg	V _{DD} ≈ 400 V, V _{GS} = 10 V, I _D = 8 A	_	60	_	nC
Gate-source charge		Q _{gs}		_	34	_	
Gate-drain ("miller") charge		Q _{gd}		_	26		

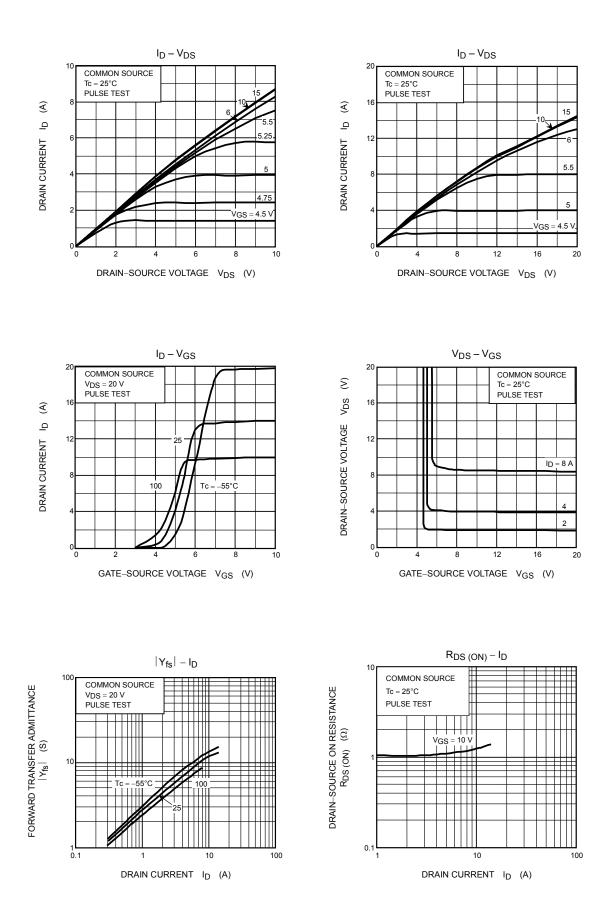
Source-Drain Ratings and Characteristics (Ta = 25°C)

Characteristic	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I _{DR}	—	_	_	8	А
Pulse drain reverse current (Note 1)	I _{DRP}	—	_	_	24	А
Forward voltage (diode)	V _{DSF}	I _{DR} = 8 A, V _{GS} = 0 V	_	_	-1.7	V
Reverse recovery time	t _{rr}	I _{DR} = 8 A, V _{GS} = 0 V dI _{DR} / dt = 100 A / μS		1700	_	ns
Reverse recovery charge	Qrr	dl _{DR} / dt = 100 A / μS	I	23		μC

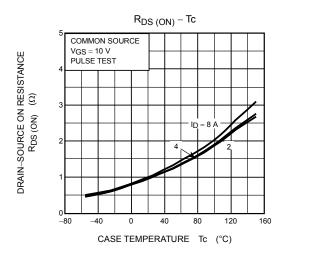
Marking

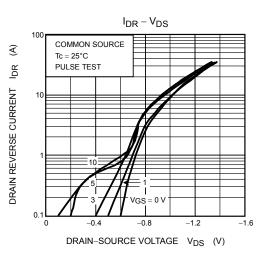


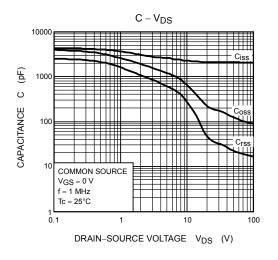
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P_D – Tc

80

CASE TEMPERATURE Tc (°C)

120

160

80

60

40

20

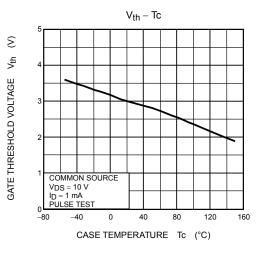
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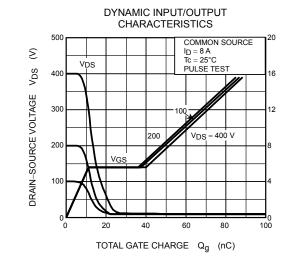
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PD

DRAIN POWER DISSIPATION



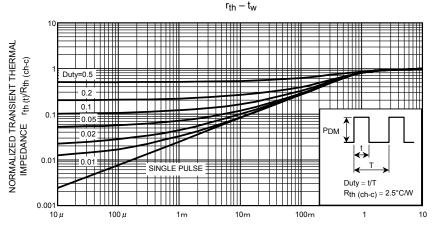


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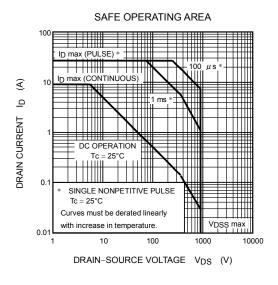
V_{GS}

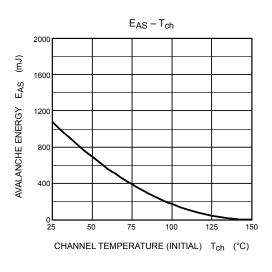
GATE-SOURCE VOLTAGE

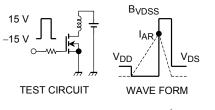
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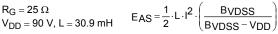












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